



# SOT1667-1

plastic, ball grid array; 256 bumps; 1.27 mm pitch; 23 mm x 23 mm x 2.54 mm body

15 December 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA
<b>Package type industry code</b>	BGA256
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	28-8-2016
<b>Manufacturer package code</b>	98ASA99291D

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	23	-	mm
E	package width	-	-	23	-	mm
A	seated height	2.12	-	2.33	2.54	mm
e	nominal pitch	-	-	1.27	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	256	-	



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## 2. Package outline

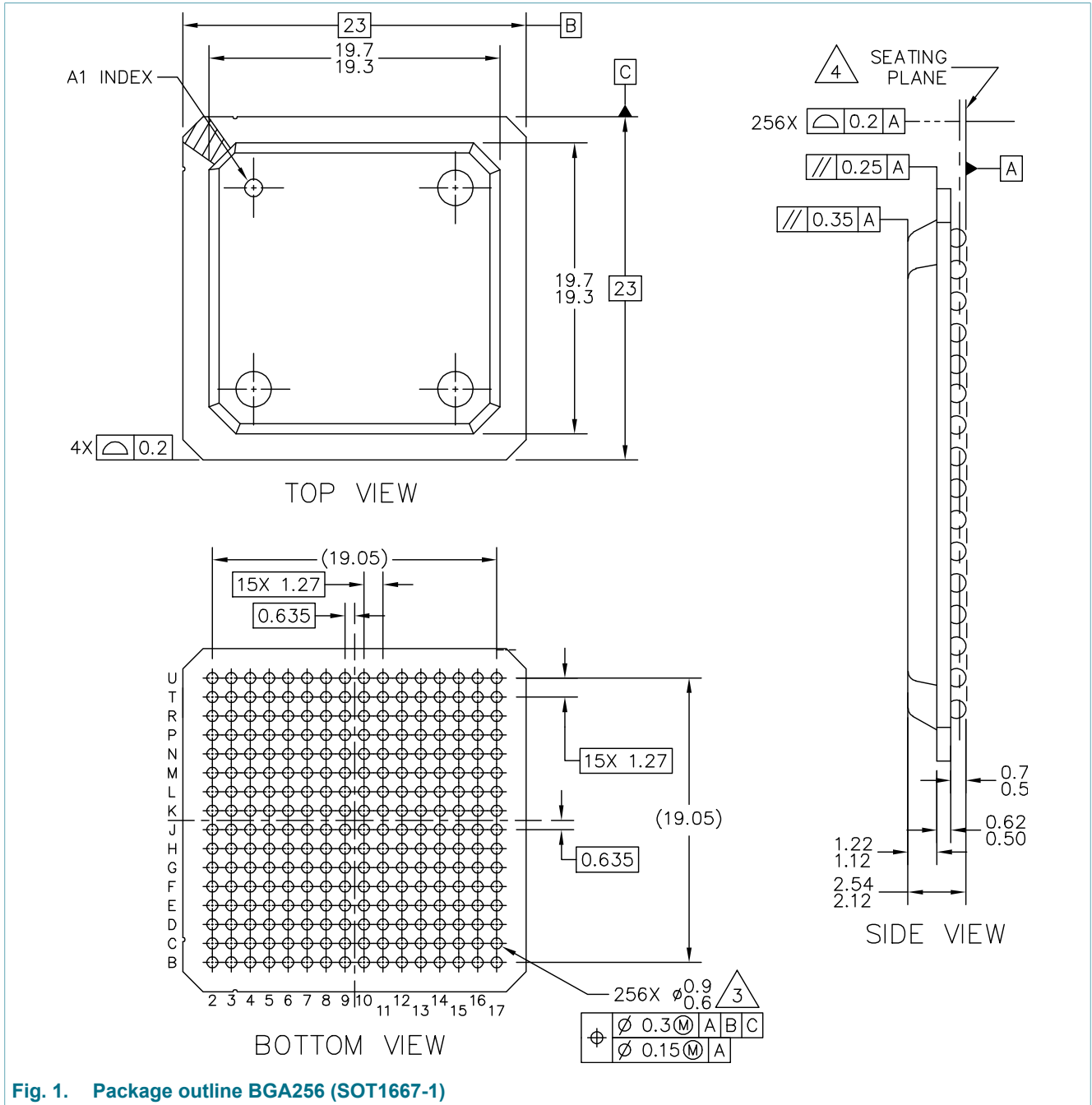


Fig. 1. Package outline BGA256 (SOT1667-1)

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## NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

**Fig. 2. Package outline note BGA256 (SOT1667-1)**

### 3. Legal information

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